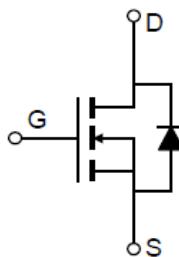


## N-Channel Super Trench Power MOSFET

### Description

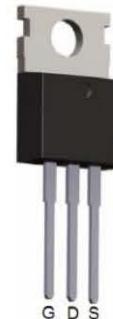
The HMS180N06A uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.



Schematic diagram



Marking and pin assignment



TO-220-3L top view

### General Features

- $V_{DS} = 60V, I_D = 120A$
- $R_{DS(ON)} = 2.1m\Omega$  (Typ) @  $V_{GS}=10V$  (Typ:  $3.5m\Omega$ )
- $R_{DS(ON)} = 3.6m\Omega$  (Typ) @  $V_{GS}=4.5V$  (Typ:  $4.0m\Omega$ )
- Excellent gate charge  $\times R_{DS(on)}$  product
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HMS180N06A	HMS180N06A	TO-220-3L	-	-	-

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous (Silicon Limited)	$I_D$	120	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	100	A
Pulsed Drain Current	$I_{DM}$	480	A
Maximum Power Dissipation	$P_D$	180	W
Derating factor		1.2	$W/C$
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	500	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	0.83	°C/W
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### Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

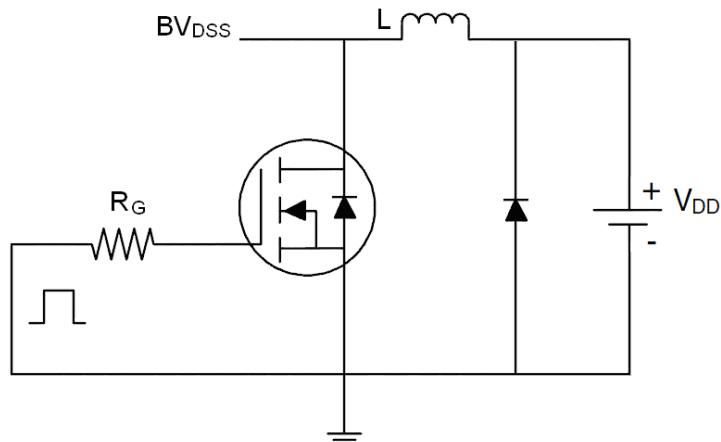
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.2	1.7	2.5	V
Drain-Source On-State Resistance	R <sub>DSS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =60A	-	2.1	2.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =60A	-	3.6	4.5	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =60A	40	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, F=1.0MHz	-	4000	-	PF
Output Capacitance	C <sub>oss</sub>		-	680	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	23	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> =60A V <sub>GS</sub> =10V, R <sub>G</sub> =4.7Ω	-	11	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	56	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	12	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V, I <sub>D</sub> =60A, V <sub>GS</sub> =10V	-	67	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	12	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	8.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =120A	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	I <sub>S</sub>		-	-	120	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = I <sub>S</sub> di/dt = 100A/μs <sup>(Note 3)</sup>	-	48	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	60	-	nC

### Notes:

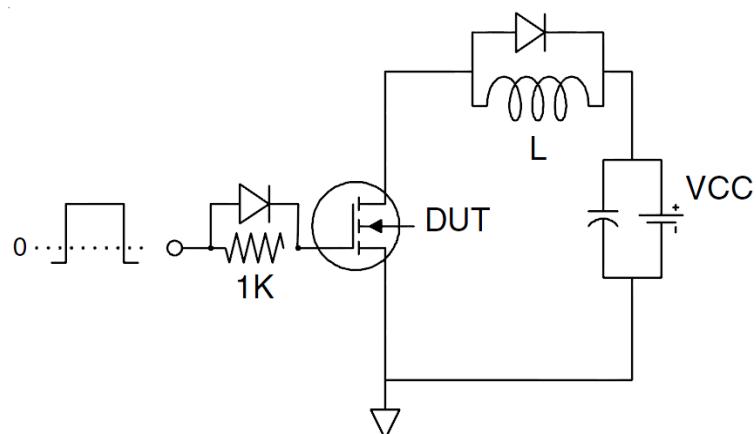
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : T<sub>j</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω

### Test Circuit

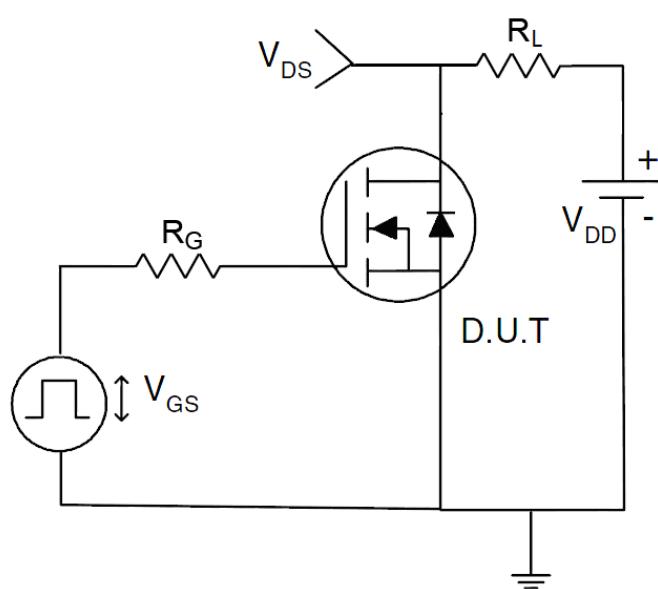
#### 1) E<sub>AS</sub> test Circuit



#### 2) Gate charge test Circuit



#### 3) Switch Time Test Circuit



### Typical Electrical and Thermal Characteristics

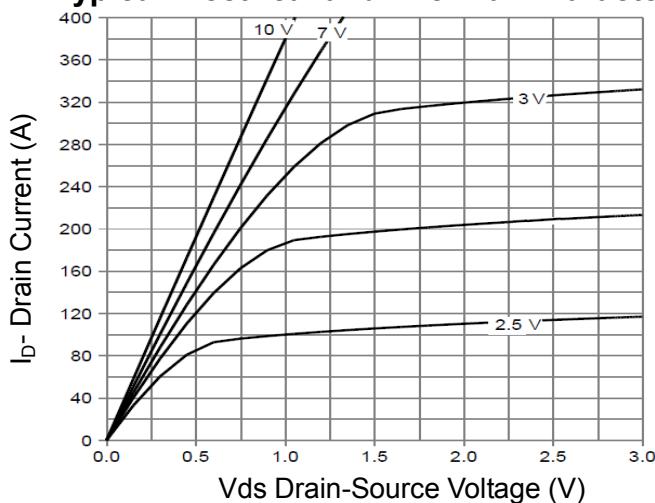


Figure 1 Output Characteristics

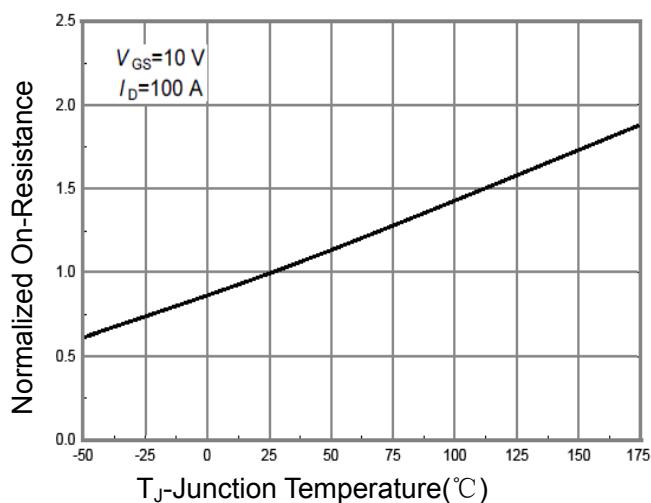


Figure 4 Rdson-JunctionTemperature

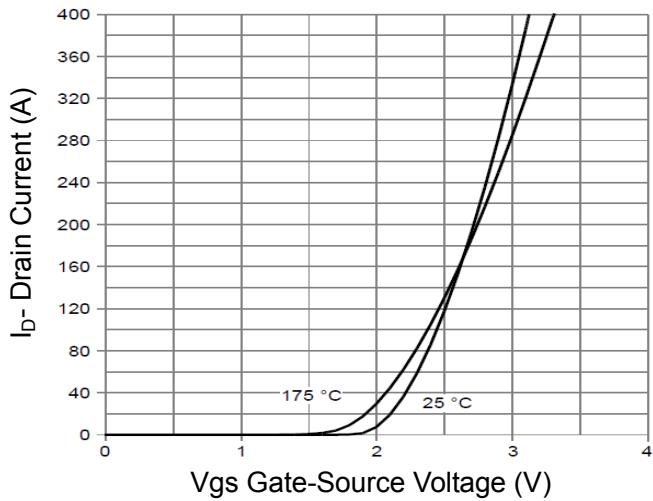


Figure 2 Transfer Characteristics

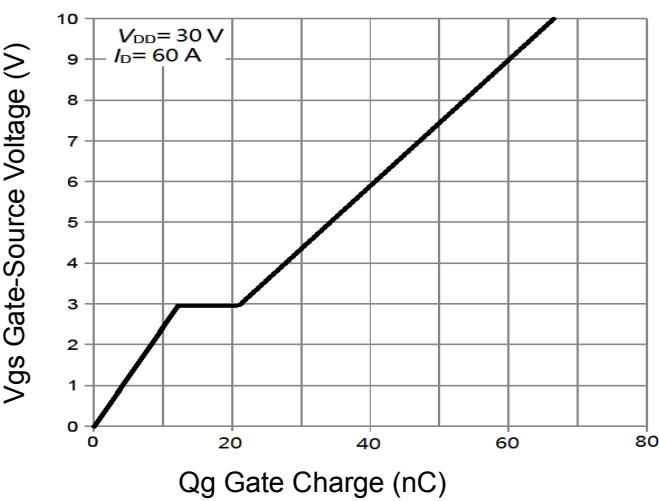


Figure 5 Gate Charge

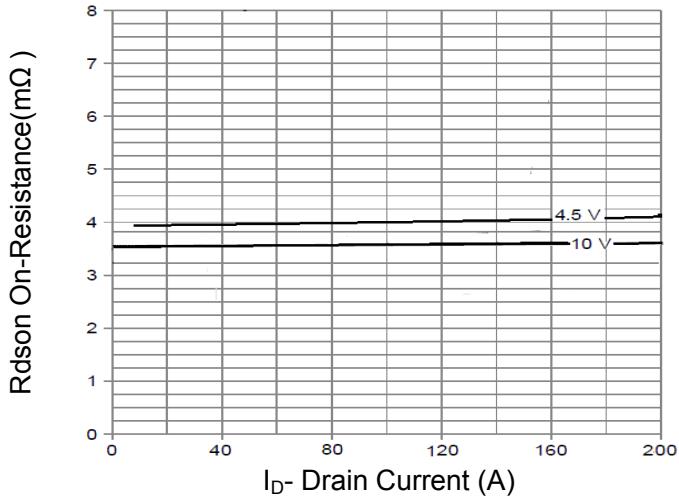


Figure 3 Rdson- Drain Current

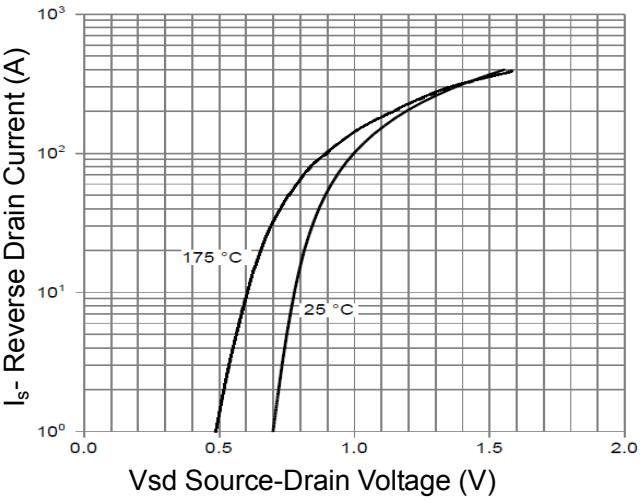


Figure 6 Source- Drain Diode Forward

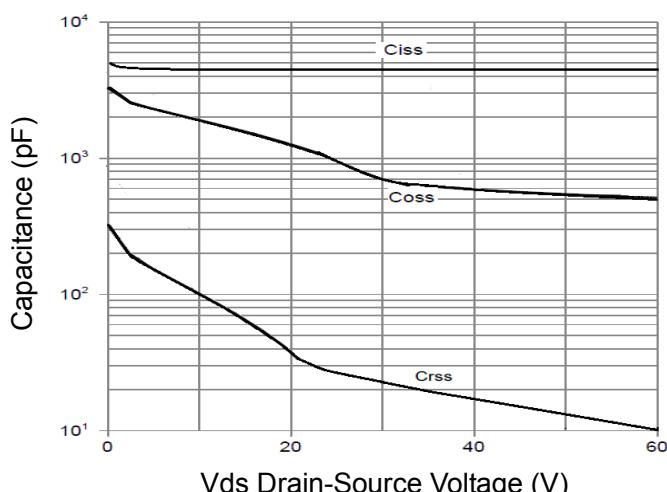


Figure 7 Capacitance vs Vds

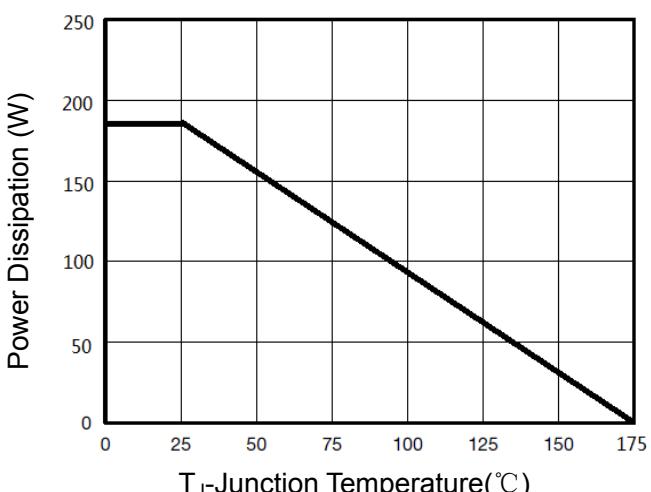


Figure 9 Power De-rating

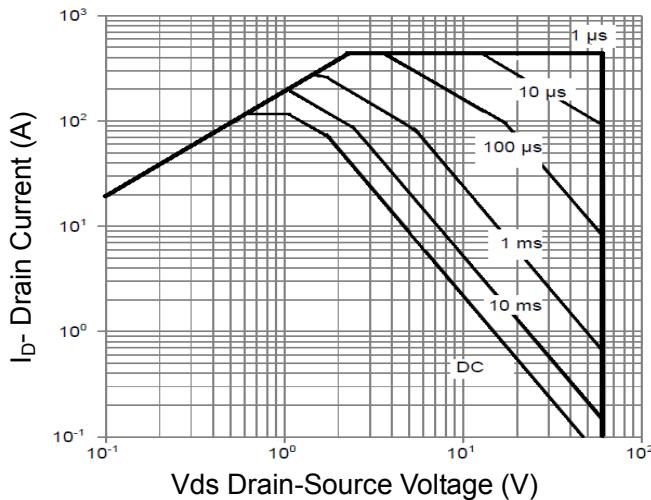


Figure 8 Safe Operation Area

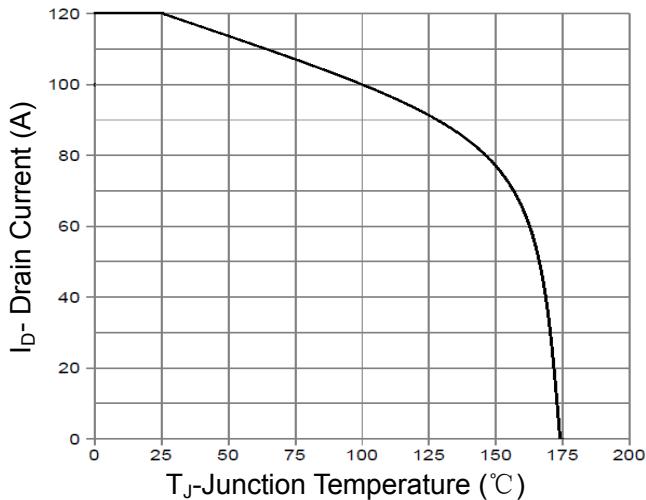
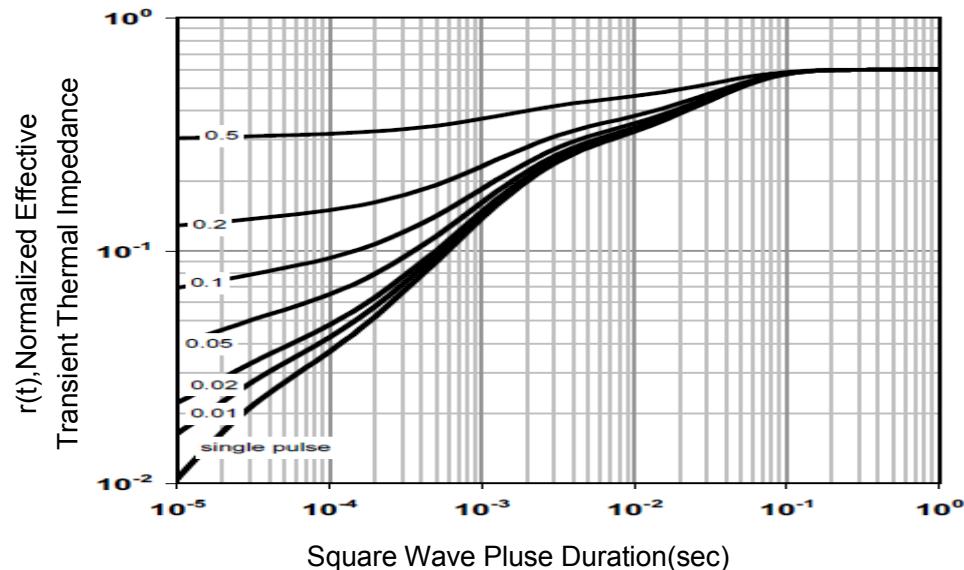
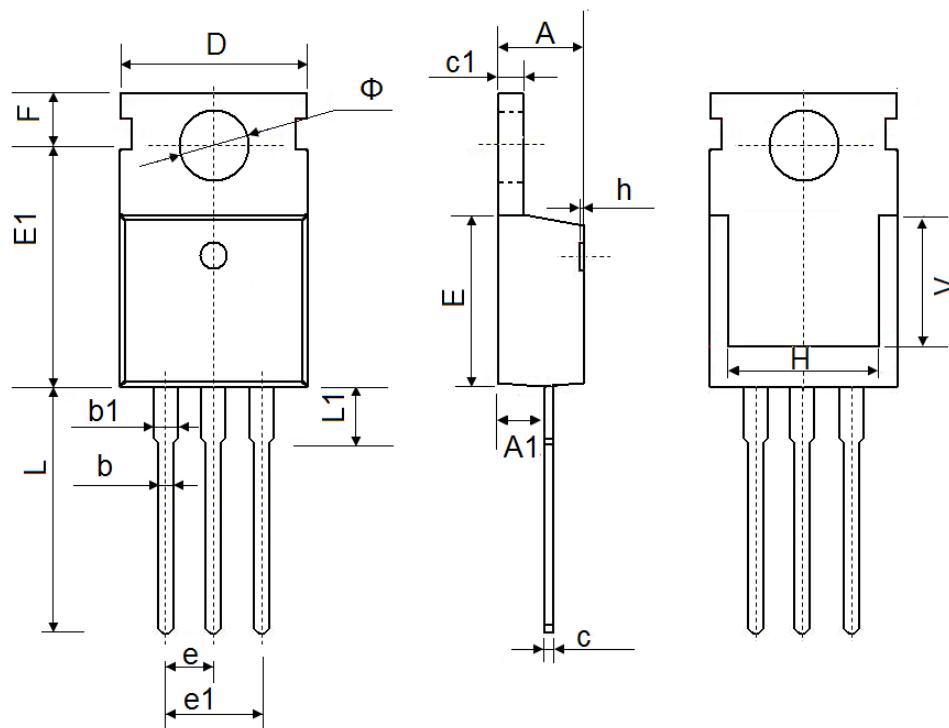


Figure 10 Current De-rating



TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150